

L Numb r	Hits	S arch Text	DB	Time stamp
-	23	(semiconductor and (package r packaging r packaged) and (stack or stacking or stacked) and (offset or off-set or offsetting or off-setting or stagger or staggered or staggering)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:33
-	2	((semiconductor and (package or packaging or packaged) and (stack or stacking or stacked) and (offset or off-set or offsetting or off-setting or stagger or staggered or staggering)).clm.) and flash and density package near5 (offset or off-set or offsetting or off-setting or stagger or staggered or staggering))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:33
-	861	package near5 (offset or off-set or offsetting or off-setting or stagger or staggered or staggering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:34
-	1110	(package or packaged or packaging) near5 (offset or off-set or offsetting or off-setting or stagger or staggered or staggering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:30
-	32	((package or packaged or packaging) near5 (offset or off-set or offsetting or off-setting or stagger or staggered or staggering)) and (flash and density)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:36
-	933	(die or package or packaging) near2 (offset or off-set)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:33
-	408	((die or package or packaging) near2 (offset or off-set)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:36
-	0	((die or package or packaging) near2 (offset or off-set)).ti,ab,clm.) and (stack or stacked or stacking) and semiconductor and flash and density and (memory or storage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:34
-	55	((die or package or packaging) near2 (offset or off-set)).ti,ab,clm.) and (stack or stacked or stacking or stackable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:35
-	30	((die or package or packaging) near2 (offs t or off-set)).ti,ab,clm.) and (tack or tacked or stacking r stackabl).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:35

-	6	(((di r packag r packaging) near2 (offset r off-set)).ti,ab,clm.) and (stack or sta ked r stacking or sta kabl).ti,ab,clm.) and (memory or storage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:36
-	20	(((die or package or packaging) near2 (offset or off-set)).ti,ab,clm.) and semiconductor) and (memory or storage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:37
-	77	(((die or package or packaging) near2 (offset or off-set)).ti,ab,clm.) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 13:41